

(1.27 mm) .050"

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Operating Temp Range:

-55 °C to +125 °C

Current Rating

(7 mm stack height):

2.7 A per pin
(10 adjacent pins powered)

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Working Voltage:

240 VAC

RoHS Compliant:

Yes (-2 Solder type only)

Lead-Free Solderable:

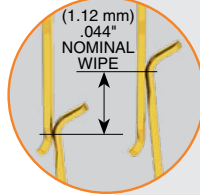
Yes

Mates with:

SEAF, SEAFP

Standoffs:

JSO



Up to 500 Pins

Low insertion/extraction forces



Solder charges

HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

PAM 4

56 Gbps

OTHER SOLUTIONS

- Up to 560 pins

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



STANDARDS

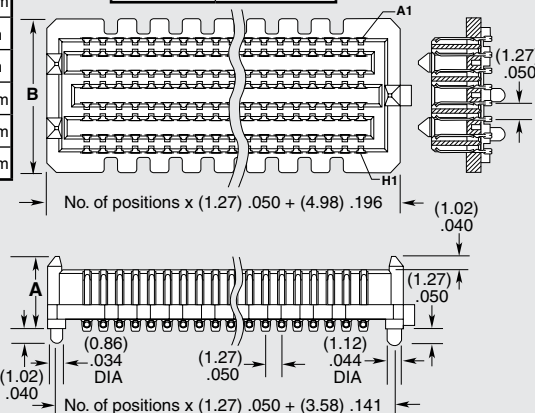
- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX
- PISMO™ 2

Visit www.samtec.com/standards for more information.

| SEAM | NO. PINS PER ROW | LEAD STYLE | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | A | K | "X"R |
|------|------------------|-------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---|------|
| | | Specify LEAD STYLE from chart | <p>–L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail</p> <p>–S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail</p> | <p>–04 = Four Rows (-06.5 not available)</p> <p>–05 = Five Rows (-06.5 not available)</p> <p>–06 = Six Rows (-06.5 not available)</p> <p>–08 = Eight Rows</p> <p>–10 = Ten Rows</p> | <p>–1 = Tin/Lead Alloy Solder Charge</p> <p>–2 = Lead-Free Solder Charge</p> | <p>–A = Alignment Pins (Required. Arrays will not self-center on solder pads)</p> <p>–K = Polyimide film Pick & Place Pad</p> <p>–TR = Tape & Reel</p> <p>–FR = Full Reel Tape & Reel Packaging (Must order max. quantities per reel. Contact Samtec for parts per reel)</p> | | |

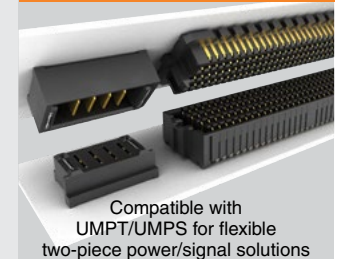
| SEAM LEAD STYLE | MATED HEIGHTS | | | |
|-----------------|-----------------|---------|---------|---------|
| | SEAF LEAD STYLE | | | |
| | –05.0 | –06.0 | –06.5 | –07.5 |
| –02.0 | 7 mm | 8 mm | 8.5 mm | 9.5 mm |
| –03.0 | 8 mm | 9 mm | 9.5 mm | 10.5 mm |
| –03.5 | 8.5 mm | 9.5 mm | 10 mm | 11 mm |
| –06.5 | 11.5 mm | 12.5 mm | 13 mm | 14 mm |
| –07.0 | 12 mm | 13 mm | 13.5 mm | 14.5 mm |
| –09.0 | 14 mm | 15 mm | 15.5 mm | 16.5 mm |
| –11.0 | 16 mm | 17 mm | 17.5 mm | 18.5 mm |

| NO. OF ROWS | B |
|-------------|--------------|
| –04 | (7.06) .278 |
| –05, –06 | (9.60) .378 |
| –08 | (12.14) .478 |
| –10 | (14.68) .578 |



| LEAD STYLE | A |
|------------|--------------|
| –02.0 | (5.61) .221 |
| –03.0 | (6.60) .260 |
| –03.5 | (7.11) .280 |
| –06.5 | (10.16) .400 |
| –07.0 | (10.59) .417 |
| –09.0 | (12.60) .496 |
| –11.0 | (14.61) .575 |

POWER/SIGNAL APPLICATION



Notes:
IPC-A-610F & IPC-J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.